

**AMENDMENTS TO THE SPECIFICATION:**

*Please amend the paragraph on page 6, lines 4-12 of the specification as follows:*

The particles to be used for producing conductive particles of the present invention are made of an organic or inorganic material. The mean particle size of the particles is not specifically limited as long as the electroless plating process is not hampered. In particular, there is no specific upper limit on the particle size because the greater the particle size is, the more easily the particles are plated. The lower limit, on the other hand, is preferably several  $\mu\text{m}$  to several ten  $\mu\text{m}$ , specifically 5 to 20  $\mu\text{m}$ .

*Please amend the paragraph on page 6, lines 13-17 of the specification as follows:*

Examples of the organic material include carbon, graphite, polytetrafluoroethylene, polyethylene, polypropylene, ABS resin, polyamide, polysulfone, AS resin, polystyrene, vinylidene chloride resin, polyphenylene ether, methyl-pentene resin, methacrylic acid resin and benzoguanamine resin.

*Please amend the paragraph on page 6, lines 18-22 of the specification as follows:*

Examples of the inorganic material include carbon, graphite, Cu, Ni, Al, Fe, Ag, Mo and W. They may be used singly or in any combination thereof. Additional examples include oxides and hydroxides such as  $\text{Al}_2\text{O}_3$ ,  $\text{SiO}_2$ ,  $\text{Ni(OH)}_2$  and  $\text{Ca(OH)}_2$ . They may also be used singly or in any combination thereof.

*Please amend the paragraph on page 10, lines 5-8 of the specification as follows:*

In this example, spherical copper powders with a mean particle size of 10 ~~2m~~ μm as inorganic material particles were plated with nickel. An electroless plating bath used here had the following composition.